



Highly Stretchable Electrode Arrays: Development and Applications

Guest Editor:

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Deadline for manuscript
submissions:

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Message from the Guest Editor

Dear Colleagues,

Flexible bioelectronics is an emerging and exciting research field with increasing demand for wearable and implantable electrodes that are reliable and compliant to tissue. Enormous effort is being expended on soft and stretchable electrode arrays.

Topics for this Special Issue may include but are not restricted to:

- Key design considerations in terms of geometries, substrates, and adhesion;
- Development of stretchable materials, including substrate and conductive electrode materials;
- Optimization of fabrication methods and strategies;
- Improved characterization methods and theoretical modeling;
- Applications for highly stretchable electrode arrays, including wearables and implantable devices;
- Reliability of devices, including durability, fatigue, long-term performance, and biocompatibility;
- Future directions and novel approaches.

For further reading, please visit the ***Special Issue website***.





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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal *Applied Sciences* has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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